

Foxconn Technology (2354.TW)



November 2024

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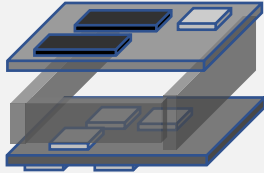
- Current Business & Outlook
- Financial Performance
- ESG Strategy
- Q&A

Current Business & Outlook



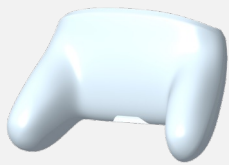
Game Console Technology Development

Game Console



Sandwich Substrate Technology

A technique of embedding three separate PCBs together to increase component density and achieve product miniaturization.



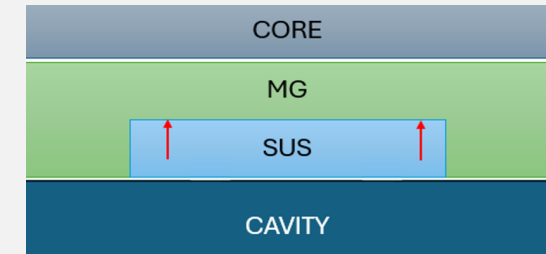
Integrated Mold Technology

Appearance Treatment Technology

- 3D inkjet printing
- Glass-like compression molding
- Ceramic injection molding (CIM)
- Metal integrated molding



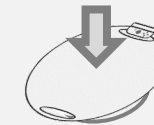
Millimeter-wave radar detection technology



Metal Injection Molding Technology

3D Magnetic Sensing Technology

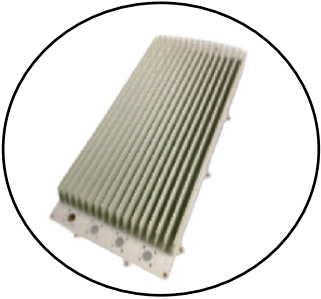
- increased lifespan
- reduced cost



Force sensing technology

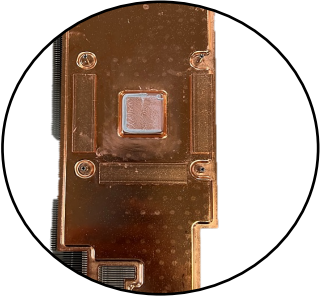


■ Thermal Module Technology Development



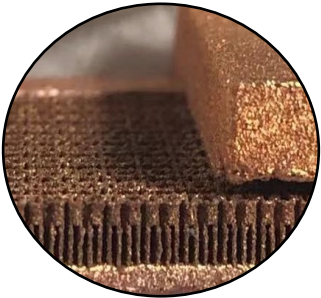
Metal Characteristic and Process

- High Heat Transfer Molding Materials: Optimize material characteristics, improve thermal transfer ability.
- Copper powder metallurgy: new materials for existing processes, expanding process application fields



Develop phase change critical components

- Thin heat pipes: Light, thin, and high Q_{max} in response to the increased weight sensitivity of wearable/handheld devices
- Vapor chamber: further improve the efficiency of air cooling, and expand the application of wattage to near kilowatt heat transfer applications.



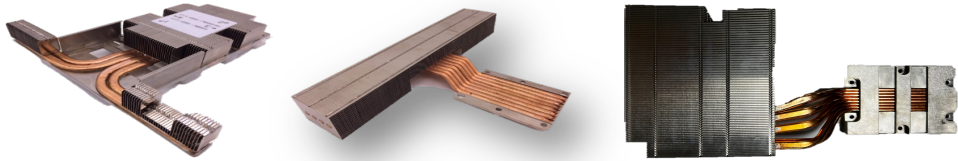
Strengthen thin film boiling production process

- Process: Cooperate with the existing process and combine 3D printing technology to provide a variety of manufacturing solutions
- Structure: Powder, net, truss structure, push up the boiling phenomenon, improve the heat exchange efficiency

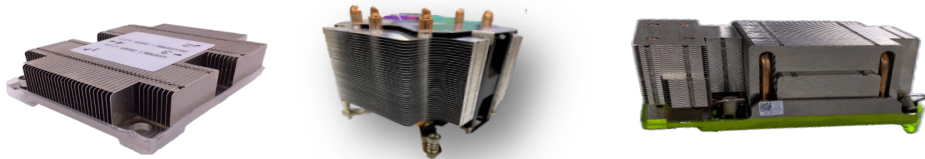
Thermal Module Technology Development

Server / Networking

TDP 60~600 Watts



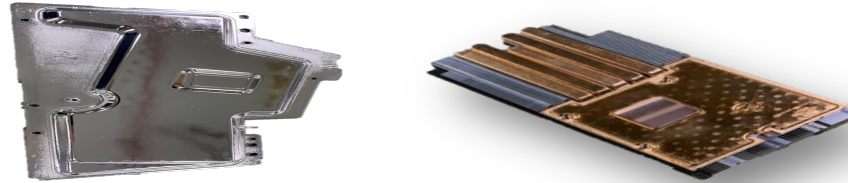
Remote Heat Exchanger (RHE): 1U- 4U



Standard Design : 1U/2U/3U/4U

HPC / AI Server

TDP 500~1000 Watts



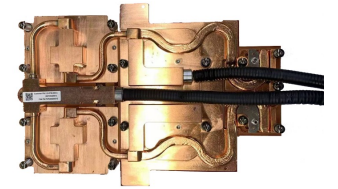
Performance VC



3D Vapor Chamber

AI Server

TDP > 1000 Watts



Coldplate



Manifold

Product images are for reference only

Fan Development Technology



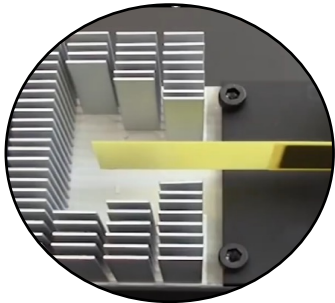
Ultra-slim fan

- 3.5mm & 4.0mm thickness + FDB bearing + 0.15mm thickness blade fan entered mass production.
- Thinner blades (0.1~0.12mm) improve fan performance, and T-FDB bearing structure greatly improves fan life and reliability.



High rpm fan



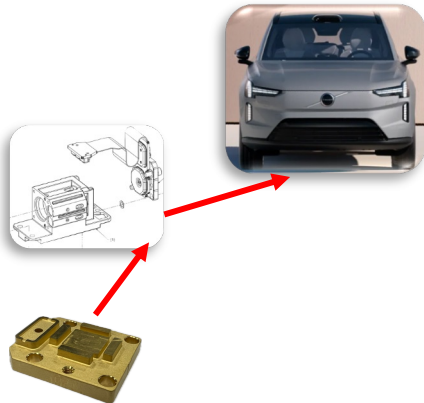

- High-speed, high-performance, high-power consumption (more than 700W), high width voltage (36~72V).
- High protection (waterproof, dustproof, anti-corrosion), anti-radiation, high reliability.



Piezoelectric fan

- Piezoelectric fan technology (design and development and manufacturing process), layout in this field in advance. Accumulate technical advantages and seize market opportunities.

Sintering Technology Development

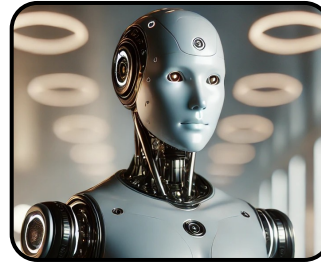
Type	Material Technology			Process
Category	Titanium Alloy	Tungsten Allow	Tungsten Copper	Bonding
Features	<ul style="list-style-type: none"> • Light weight and high strength (high specific strength) • Excellent corrosion resistance 	<ul style="list-style-type: none"> • High proportion • Can be customized 	<ul style="list-style-type: none"> • Low thermal expansion coefficient • High thermal conductivity 	<ul style="list-style-type: none"> • Take advantage of different material properties to enhance functionality and application flexibility.
Difficulty	<ul style="list-style-type: none"> • High vacuum sintering requirements • Precise control of metallurgical phases (alpha, beta, etc. 	<ul style="list-style-type: none"> • Segregation Control of Mechanized Alloy Composition Phases • decorative surface treatment 	<ul style="list-style-type: none"> • Improved affinity between tungsten and copper elements • Copper coating technology on tungsten powder surface 	<ul style="list-style-type: none"> • Analysis of Interface Metallurgical Behavior of Dissimilar Metals • Different material bonding strength processing
Application	<p><u>Sports Equipment</u></p> 	<p><u>Sports industry</u></p> 	<p><u>Automotive Industry</u></p> 	<p><u>Automotive Industry</u></p> 

■ Light Metal Development

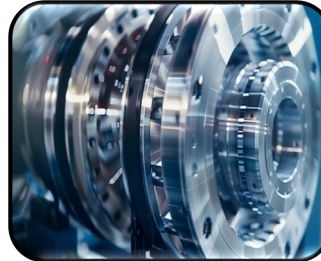
- **Giga Diecasting & Heat Treatment for Structural Parts**
- **Semi-Solid Forming**
- **Hollow Structure Processes**
- **Diecasting Alloys Development**



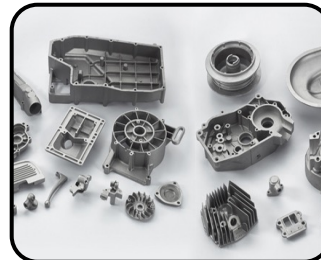
**Edge AI
Casing**



**Robotics
Components**

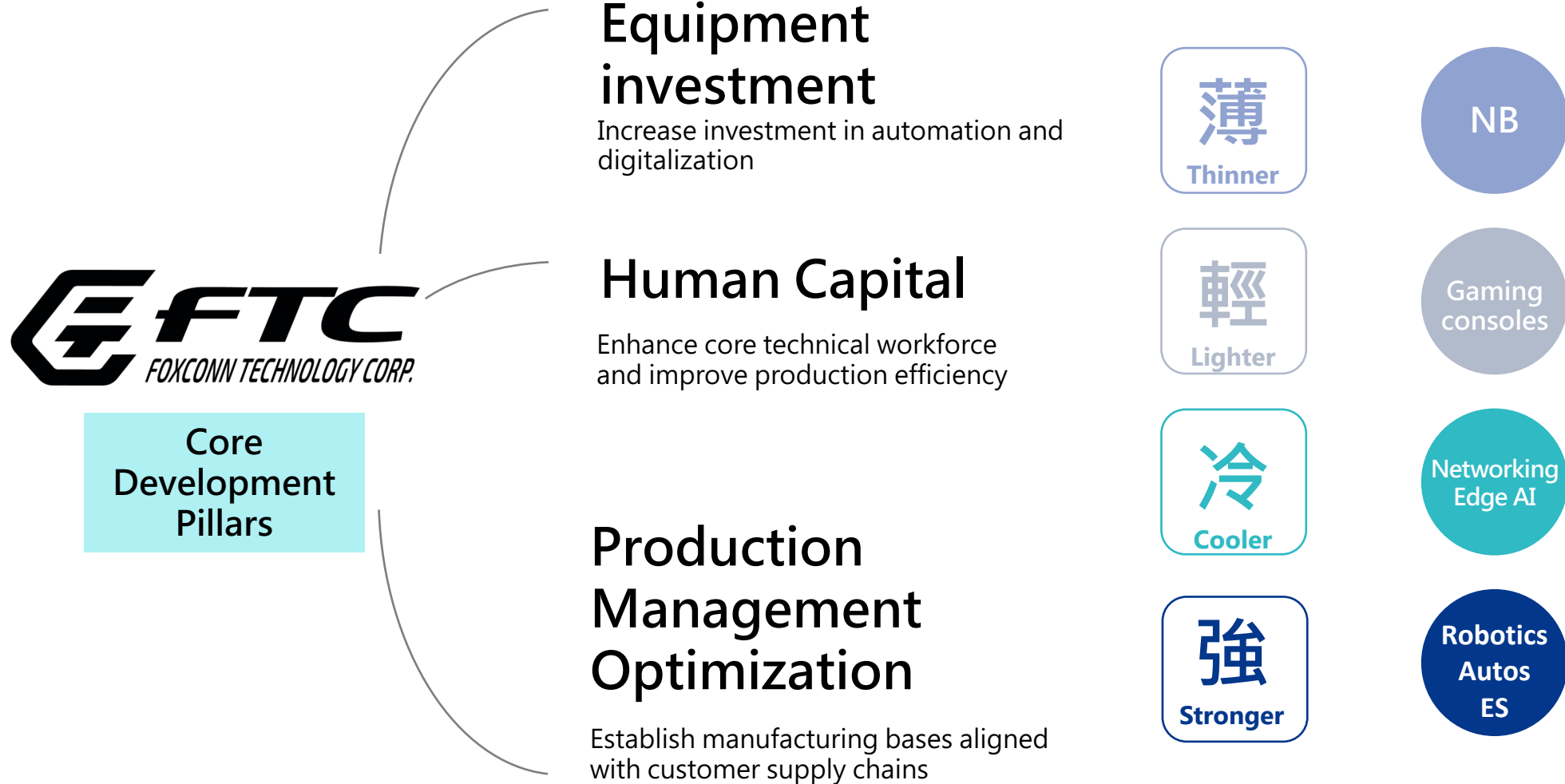


**Energy Storage
Components**



**Auto
Parts**

Development Strategy

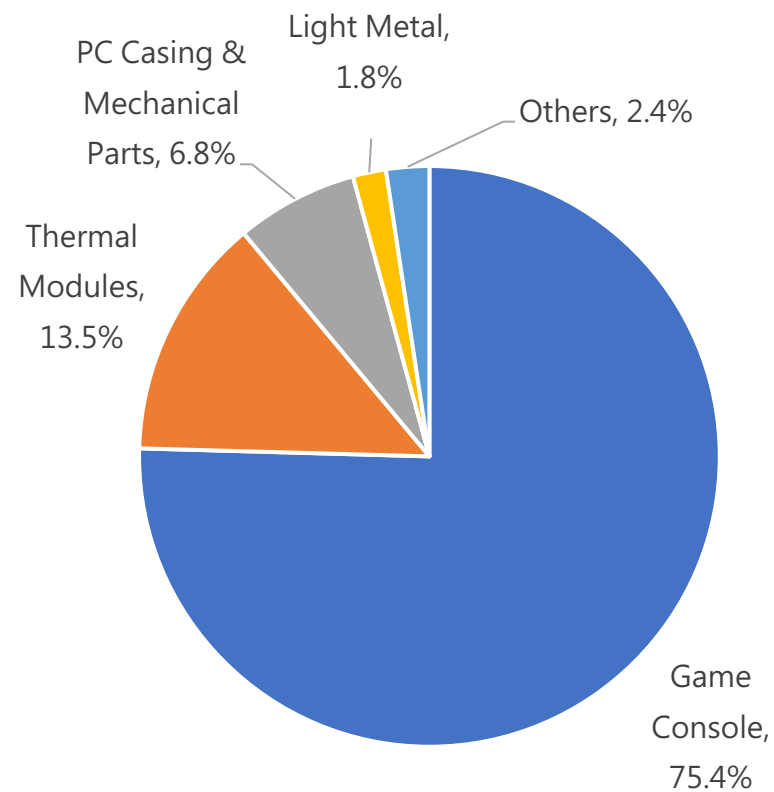


Financial Performance

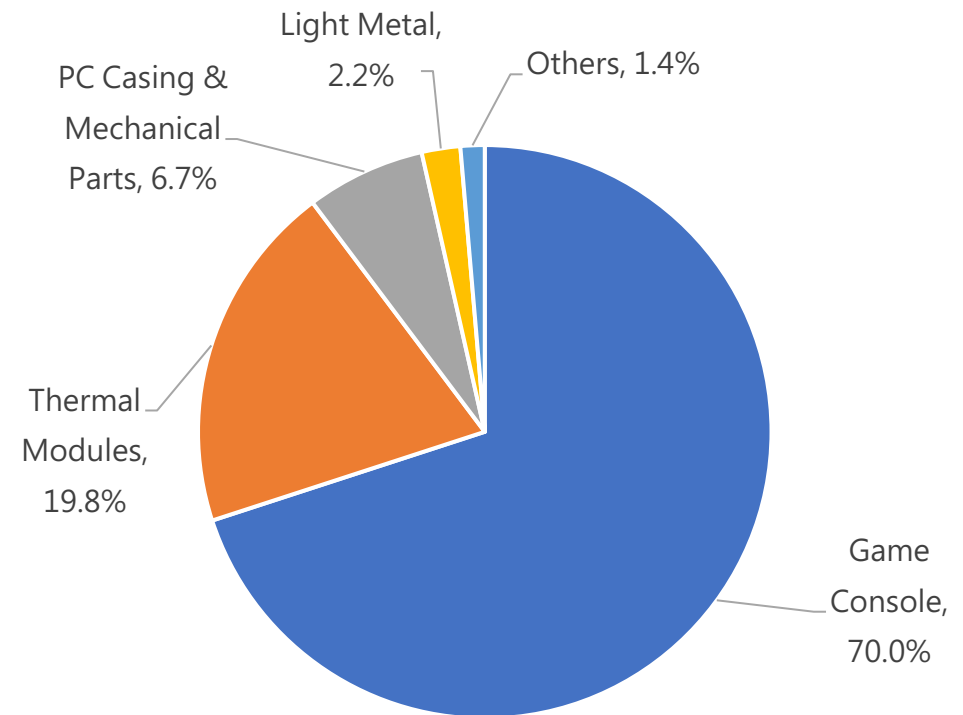


Product Segments

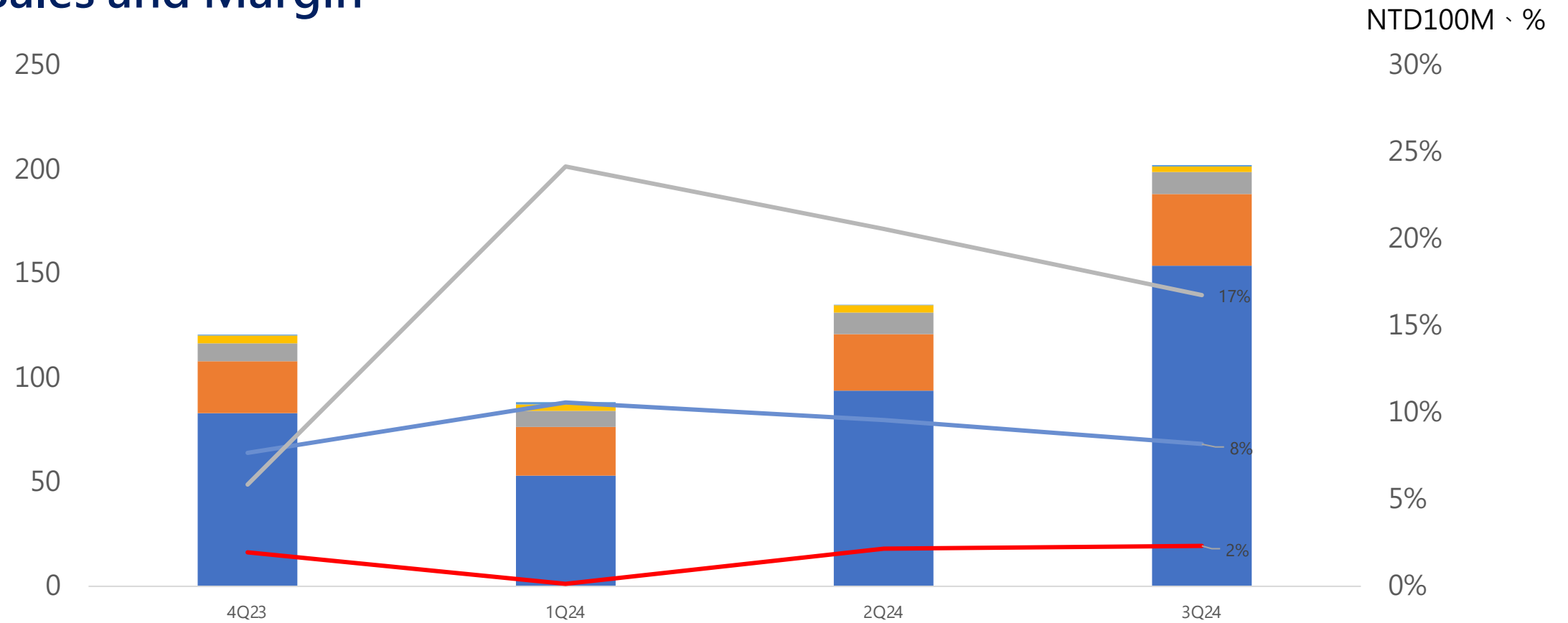
2023 1~3Q



2024 1~3Q

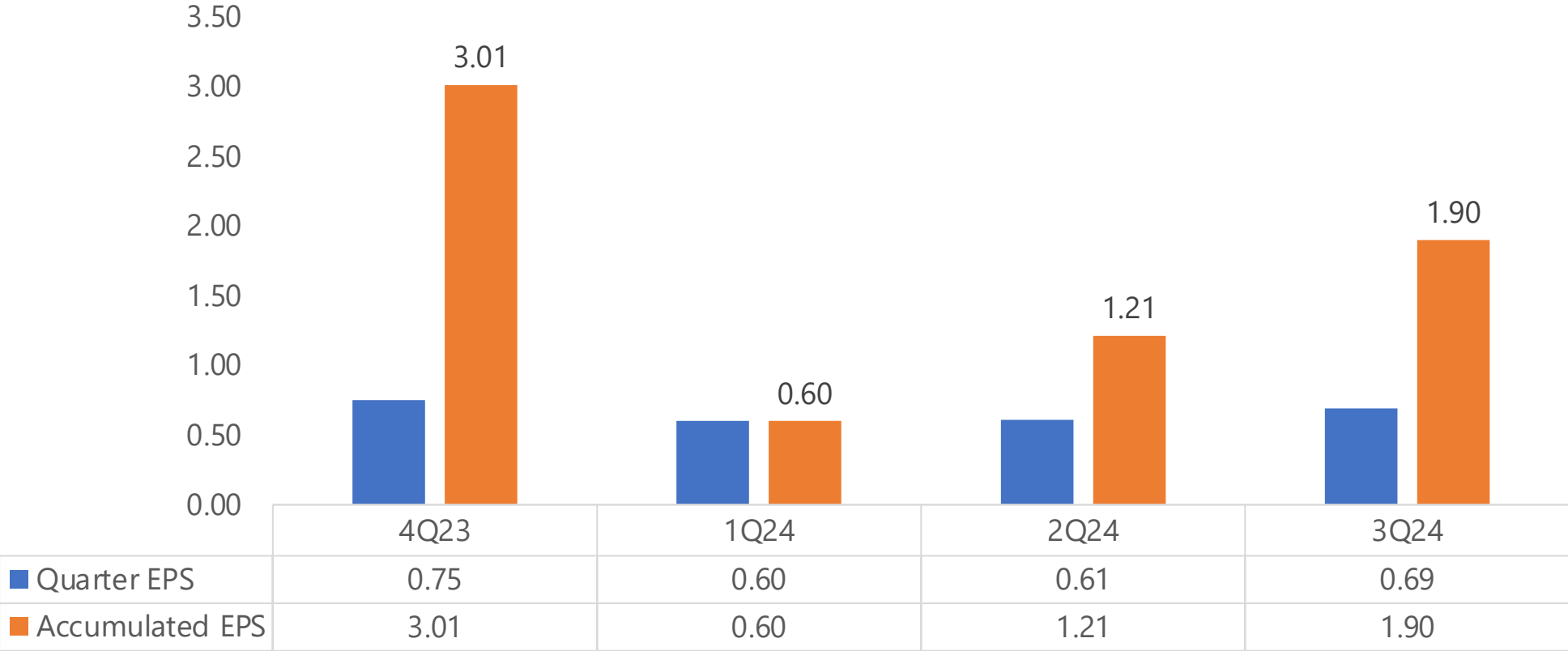


Sales and Margin



Game Console Thermal Module Casing Light Metal Others GPM OPM NPM

■ EPS



2024Q4 Outlook

2024
Q4

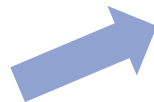
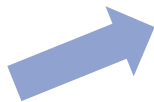
Game
Console

Casing

Thermal
Module

Others

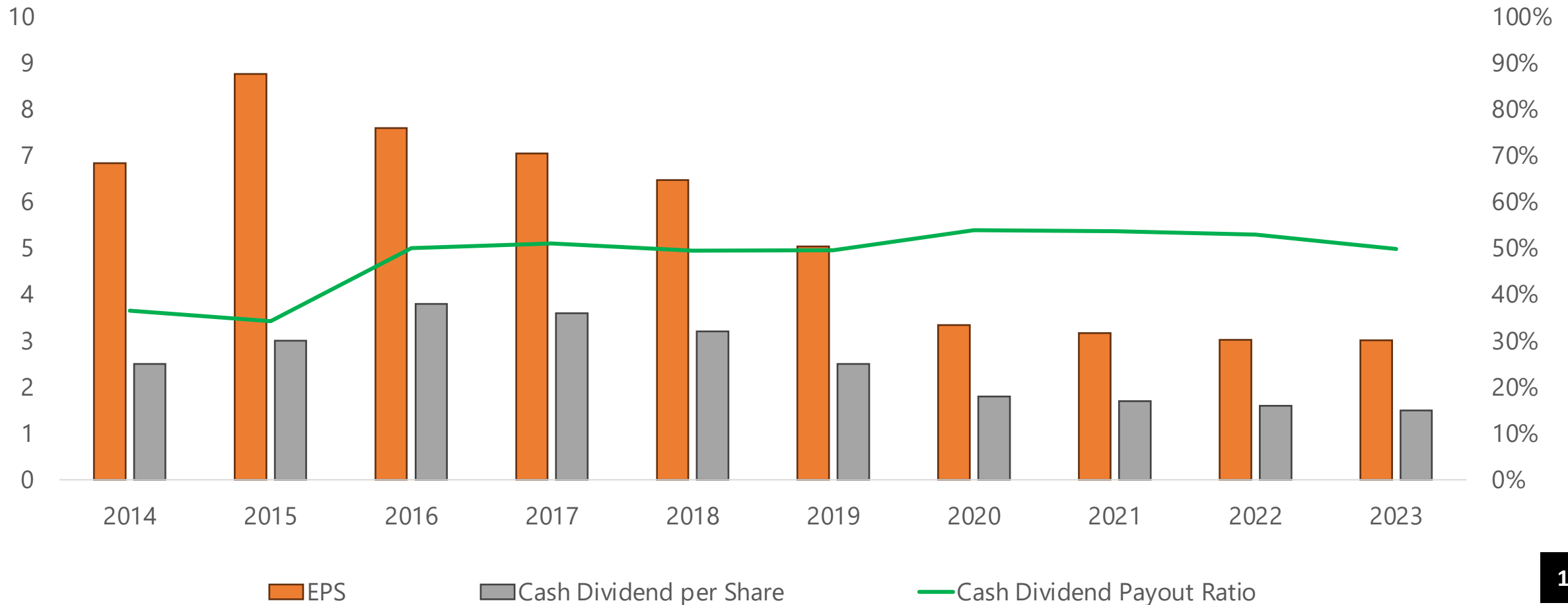
QoQ



YoY



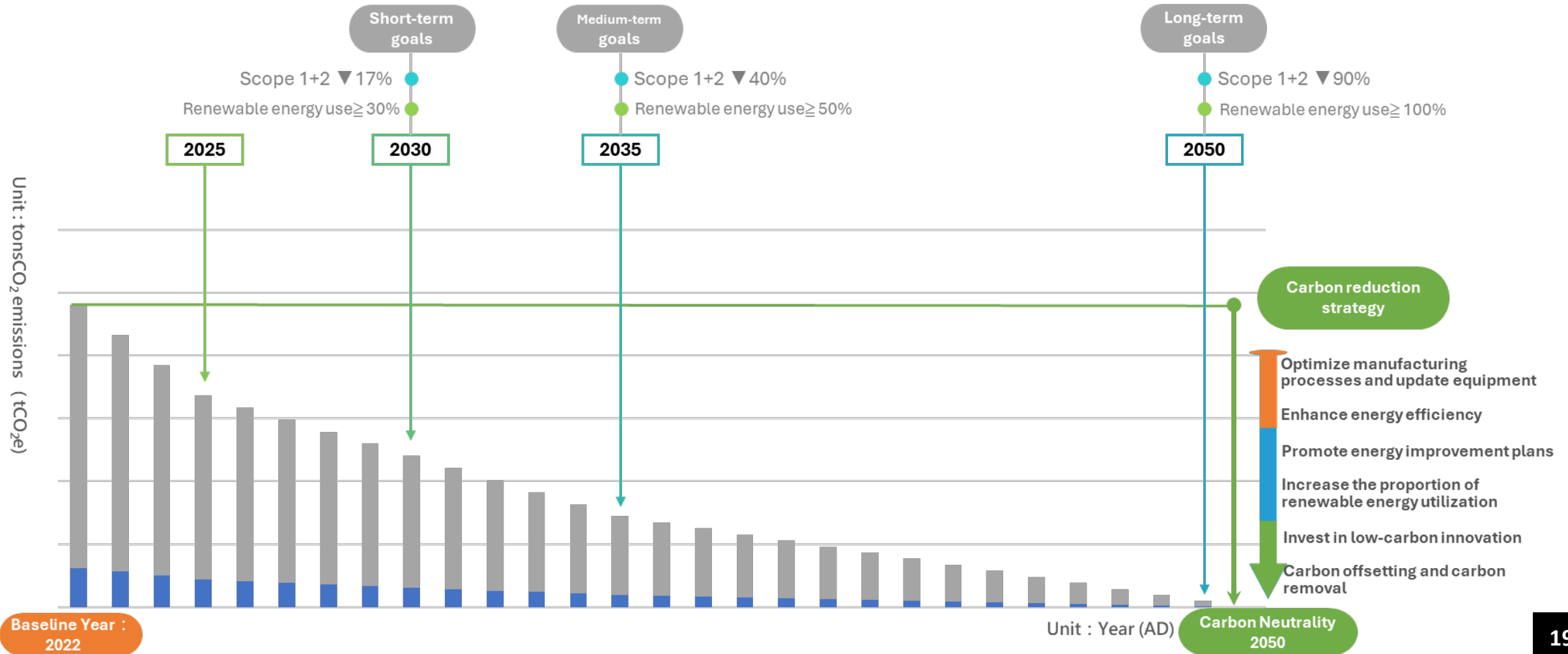
Earnings & Dividend Policy



ESG and Sustainability Strategy



Carbon Neutrality Strategic Metrics and Targets



UL2799 certification

UL Solutions is pleased to present this letter to:

Congratulations to the company for having achieved:

Environmental Claim Validation

for:

YanTai Fu Zhun Precision Electronics Co., Ltd.
No. 18, Changsha Street, Yantai Economic And Technological Development Zone, Yantai Area, China (Shandong) Pilot Free Trade Zone, China.

This facility has achieved Zero Waste to Landfill Platinum Operations, 100% diversion, with 10% Thermal Processing with Energy Recovery as per Environmental Claim Validation Procedure (ECVP) for Zero Waste Classifications, UL 2799A First Edition per UL Project 4791188202

This achievement letter is not a product certificate, and it does not indicate the current status of a product or facility's certification/Validation. Please confirm the current status of a certification/Validation by searching the UL SPOT® Product Database at [UL.com/spot](https://ul.com/spot) or by emailing LST.ULE.ProgramAdministration@ul.com.

08/23/2024 – 08/23/2025


Validation period



Josh Warren
VP&GM, Retail & Consumer Products



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ENVIRONMENTAL CLAIM VALIDATION SUMMARY

Hon Hai Technology Group (Foxconn)

Champ Tech Optical (Foshan) Corporation

Report Number:
340011-4160



Validation Period:
26 Sep 2024 - 26 Sep 2025

Claim:
Champ Tech Optical (Foshan) Corporation has achieved Zero Waste to Landfill Gold Operations, 98% diversion, with 8% Thermal Processing with Energy Recovery.

Method:
Environmental Claim Validation Procedure (ECVP) for Zero Waste Classifications, UL ECVP 2799A Zero Waste to Landfill

Facility:
No.35, Huabao North Road, Chengxi Industrial Zone Chancheng District, Foshan City, Guangdong, 528051, CHINA

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Q&A

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